

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.19947	100.0	10.6029
			Subtotal	0.19947	100	10.6029
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01335	10.0	0.70985
	Silver alloy	Silver (Ag)	7440-22-4	0.00267	2.0	0.14197
	Lead alloy	Lead (Pb)	7439-92-1	0.11751	88.0	6.24666
			Subtotal	0.13353	100	7.09848
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.35179	100.0	18.7
			Subtotal	0.35179	100	18.7
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	1.08529	3.0	57.69
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.17058	6.0	115.38
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	3.61763	10.0	192.3
	Carbon Black	Carbon black	1333-86-4	0.18088	0.5	9.615
	Filler	Misc. Silica compounds (generic)	14808-60-7	28.21748	78.0	1,499.94
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.90441	2.5	48.075
			Subtotal	36.17627	100	NaN
Adhesive		Dicyandiamide (generic)	461-58-5	0.00141	5.0	0.075
	Lead alloy	Silica -amorphous-	7631-86-9	0.00988	35.0	0.525
	Polymer	Epoxy resin system		0.01693	60.0	0.9
			Subtotal	0.02822	100	1.5
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0315	0.05	1.67455
	Copper alloy	Iron (Fe)	7439-89-6	0.09451	0.15	5.02365
	Copper alloy	Copper (Cu)	7440-50-8	62.87862	99.8	3,342.4018
			Subtotal	63.00463	100	NaN
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.1061	100.0	5.64
			Subtotal	0.1061	100	5.64
			Total	100.00001	100	NaN

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